

In the Claims:

Please cancel claims 47, 54, 56, 57, 78, 80, and 81. Please amend claims 1, 41, 88, and 94. The claims are as follows:

1. (Currently amended) An encapsulant composition comprising:

a resin material selected from the group consisting of epoxy and cyanate ester resins;

a flexibilizing agent comprising 2 percent to about 5 percent by weight of said

composition; and

a filler material comprising substantially spherical or spheroidal particles, each particle having a diameter of less than about 41 microns,

wherein the composition has a higher fracture toughness, a lower viscosity, and increased thermal shock resistance at a temperature excursion below -40 °C, or combinations thereof than the composition would have if the flexibilizing agent were not present in the composition.

wherein the flexibilizing agent is a flexibilizer blend comprising a first flexibilizer and a thermoplastic, wherein the composition has a higher fracture toughness and lower viscosity than the composition would have if the flexibilizer blend were not present in the composition, wherein the thermoplastic is separated from the resin to form a two-phase morphology, and wherein the first flexibilizer provides groups that connect crosslink sites in a network of the composition.

2-13. (Canceled)

14. (Previously presented) The composition of claim 1, wherein a portion of each of said

09/778,996

spherical or spheroidal particles includes a layer of coupling agent positioned thereon, and wherein the coupling agent comprises about 0.25% by weight of the filler material.

15-17. (Canceled)

18. (Previously presented) An electronic package comprising:

- a substrate having an upper surface;
- a semiconductor chip mounted on a portion of said upper surface of said substrate and electrically coupled to said substrate, said semiconductor chip having a bottom surface and at least one edge surface being substantially perpendicular to said bottom surface; and
- a material positioned on at least said portion of said upper surface of said substrate and against at least a portion of said at least one edge surface of said semiconductor chip, said material being the encapsulant composition of claim 1.

19-40. (Canceled)

41. (Currently amended) A method of making an encapsulant composition, the method comprising the steps of:

- providing a first quantity of resin material;
- adding to said first quantity of resin material a second quantity of flexibilizing agent by homogenizing said flexibilizing agent in said first quantity of resin material by reacting said resin material and said flexibilizing agent together at a temperature of greater than about 100 degrees

09/778,996

Celsius;

adding to said first quantity of resin material a third quantity of filler material comprising substantially spherical or spheroidal particles, each particle having a diameter of less than about 41 microns; and

blending said resin material, wherein after said blending said flexibilizing agent comprises 2 percent to about 5 percent by weight of said composition,

wherein immediately after the steps of adding the flexibilizing agent and adding the filler material have been performed the composition is uncured and the composition is stable for a time period at least 12 hours,

wherein the composition has a higher fracture toughness, a lower viscosity, and increased thermal shock resistance at a temperature excursion below -40 °C, or combinations thereof than the composition would have if the flexibilizing agent were not present in the composition,

wherein the flexibilizing agent is a flexibilizer blend comprising a first flexibilizer and a thermoplastic, wherein the composition has a higher fracture toughness and lower viscosity than the composition would have if the flexibilizer blend were not present in the composition, wherein the thermoplastic is separated from the resin to form a two-phase morphology, and wherein the first flexibilizer provides groups that connect crosslink sites in a network of the composition.

42. (Canceled)

43. (Previously presented) The method of claim 41, wherein said step of blending is performed under vacuum.

09/778,996

44. (Previously presented) The method of claim 43, wherein said step of blending is performed under vacuum at a pressure of about 5 millimeters of mercury.

45. (Canceled)

46. (Previously presented) The method of claim 41, wherein a portion of each of said spherical or spheroidal particles includes a layer of coupling agent positioned thereon, and wherein the coupling agent comprises about 0.25% by weight of the filler material.

47-50. (Canceled)

51. (Previously presented) The composition of claim 1, wherein the composition has a higher fracture toughness than the composition would have if the flexibilizing agent were not present in the composition, wherein the flexibilizer is homogeneously blended with the resin, and wherein the flexibilizer is adapted to chemically react with the resin material during a thermally induced chemical reaction.

52. (Previously presented) The composition of claim 1, wherein the composition has a lower viscosity than the composition would have if the flexibilizing agent were not present in the composition.

53. (Previously presented) The composition of claim 1, wherein the composition has increased

09/778,996

thermal shock resistance at a temperature excursion below -40 °C than the composition would have if the flexibilizing agent were not present in the composition.

54-57. (Canceled)

58. (Previously presented) The composition of claim 1, wherein the resin material consists of epoxy resins, wherein the composition further comprises a surfactant comprising that facilitates mixing the filler with the epoxy resins, wherein the surfactant comprises non-ionic type surface active agents, and wherein the surfactant comprises between about 0.5% and about 3% by weight of the composition.

59. (Previously presented) The composition of claim 1, wherein the filler material has a negative coefficient of thermal expansion.

60. (Previously presented) The composition of claim 1, wherein the composition further comprises an organic dye comprising less than about 0.2% by weight of the composition.

61. (Previously presented) The composition of claim 1, wherein the composition further comprises non-reactive organic solvents comprising less than about 0.2% by weight of the composition or the composition is completely free of non-reactive organic solvents.

62. (Previously presented) The composition of claim 1, wherein the composition is cured and has

09/778,996

a coefficient of thermal expansion between about 25 and about 40 ppm/ $^{\circ}$ C, a glass transition temperature between about 140 $^{\circ}$ and about 190 $^{\circ}$ C, and a Shore D hardness greater than about 90.

63-74. (Canceled)

75. (Previously presented) The method of claim 41, wherein the composition has a higher fracture toughness than the composition would have if the flexibilizing agent were not present in the composition, wherein the flexibilizer is homogeneously blended with the resin, and wherein the flexibilizer is adapted to chemically react with the resin material during a thermally induced chemical reaction.

76. (Previously presented) The method of claim 41, wherein the composition has a lower viscosity than the composition would have if the flexibilizing agent were not present in the composition.

77. (Previously presented) The method of claim 41, wherein the composition has increased thermal shock resistance at a temperature excursion below -40 $^{\circ}$ C than the composition would have if the flexibilizing agent were not present in the composition.

78-81. (Canceled)

82. (Previously presented) The method of claim 41, wherein the resin material consists of epoxy

09/778,996

resins, wherein the composition further comprises a surfactant comprising that facilitates mixing the filler with the epoxy resins, wherein the surfactant comprises non-ionic type surface active agents, and wherein the surfactant comprises between about 0.5% and about 3% by weight of the composition.

83. (Previously presented) The method of claim 41, wherein the filler material has a negative coefficient of thermal expansion.

84. (Previously presented) The method of claim 41, wherein the composition further comprises an organic dye comprising less than about 0.2% by weight of the composition.

85. (Previously presented) The method of claim 41, wherein the composition further comprises non-reactive organic solvents comprising less than about 0.2% by weight of the composition or the composition is completely free of non-reactive organic solvents.

86. (Previously presented) The method of claim 41, wherein after the substantially curing step, the composition has a coefficient of thermal expansion between about 25 and about 40 ppm/ $^{\circ}$ C, a glass transition temperature between about 140 $^{\circ}$ and about 190 $^{\circ}$ C, and a Shore D hardness greater than about 90.

87. (Previously presented) The composition of claim 1, wherein the resin material consists of epoxy resins, and wherein the epoxy resins comprise 3',4'-epoxycyclohexylmethyl

09/778,996

3,4-epoxycyclohexanecarboxylate.

88. (Currently amended) The composition of claim 54 1, wherein the thermoplastic comprises a poly(arylene) ether, and wherein the first flexibilizer comprises bis(2,3-epoxy-2-methylpropyl)ether.

89. (Previously presented) The composition of claim 1, wherein the filler material comprises zirconium tungstate.

90. (Previously presented) The composition of claim 14, wherein the coupling agent comprises b-(3,4-epoxycyclohexyl) ethyltrimethoxy silane.

91. (Previously presented) The composition of claim 58, wherein the surfactant comprises polyethylene glycol-p-tert-octylphenyl ether.

92. (Previously presented) The composition of claim 60, wherein the organic dye comprises nigrosine.

93. (Previously presented) The method of claim 41, wherein the resin material consists of epoxy resins, and wherein the epoxy resins comprise 3',4'-epoxycyclohexylmethyl 3,4-epoxycyclohexanecarboxylate.

94. (Currently amended) The method of claim 78 41, wherein the thermoplastic comprises a poly(arylene) ether, and wherein the first flexibilizer comprises bis(2,3-epoxy-2-methylpropyl)ether.

95. (Previously presented) The method of claim 41, wherein the filler material comprises zirconium tungstate.

96. (Previously presented) The method of claim 46, wherein the coupling agent comprises b-(3,4-epoxycyclohexyl) ethyltrimethoxy silane.

97. (Previously presented) The method of claim 82, wherein the surfactant comprises polyethylene glycol-p-tert-octylphenyl ether.

98. (Previously presented) The method of claim 84, wherein the organic dye comprises nigrosine.